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Van Der Sluis-Van Der Voort et al.

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[54]	METHOD OF PHOTOLITHOGRAPHICALLY
	PRODUCING A COPPER PATTERN ON A
	PLATE OF AN ELECTRICALLY
	INSULATING MATERIAL

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[58] Field of Search					

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[57] ABSTRACT

A method of forming copper patterns on a selection plate for a display, the selection plate having a plurality of holes. The method provides copper patterns that form selected tracks on the selection plate and that are disposed internally of selected holes, the copper patterns being sealed with a corrosion-resistant layer of nickel-phosphorous. The method includes steps of forming a copper layer on at least one surface of the selection plate, forming a layer of nickel-boron on the copper layer, using cataphoretic lithographic processing to form the desired patterns, and providing a nickel-phosphorous layer to seal the patterns.

20 Claims, 1 Drawing Sheet

